IN24AA02

2K 1.8V CMOS Serial EEPROMs

DESCRIPTION

IN24AA02 is a 2K-bit Electrically Erasable PROM. The device is organized as a single block of 256x8 bit memory with a two-wire serial interface. Low voltage design permits operation down to 1.8V with standby and active currents of only 1μ A and 3mA respectively. The IN24AA02 also has a page-write capability for up to 8 bytes of data.

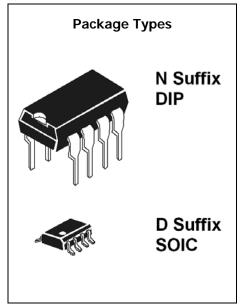
FEATURES

- Single supply with operation down to 1.8V
- Two version:
 - Version A pins A0, A1, A2 are using for the addressing on a single bus system (up to eight ICs),
 - Version B pins A0, A1, A2 are not using. Only one IC may be using on a bus.
- Low power CMOS technology
- Organized as a single block of 256 bytes (256x8)
- Two wire serial interface bus, IIC compatible
- Schmitt trigger, filtered inputs for noise suppression
- Output slope control to eliminate ground bounce
- 100 kHz (1.8V) and 400 kHz (2.5-5.5V) compatibility
- Self-timed write cycle (including auto-erase)
- Page-write buffer for up to 8 bytes
- 6 ms typical write cycle time for page-write
- Hardware write protect for entire memory
- Can be operated as a serial ROM
- Factory programming (QTP) available
- ESD protection > 2,000V
- 1,000,000 ERASE/WRITE cycles guaranteed
- Data retention > 200 years
- 8-pin DIP, 8-pin SOP
- Temperature range -40°C to +85°C (industrial)

PINNING

| Function |
|-----------------------------------|
| Ground |
| Serial Address/Data I/O |
| Serial Clock |
| Write Protect Input |
| +1.8V to 5.5V Power Supply |
| Pins for device address selection |
| |

Note: Pins A0, A1 & A2 are not used for IN24AA02B (No internal connections)



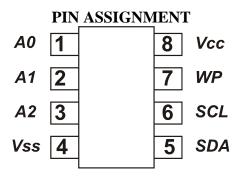
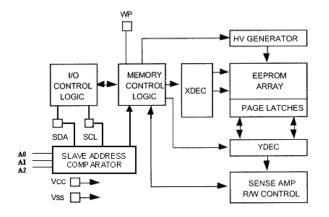
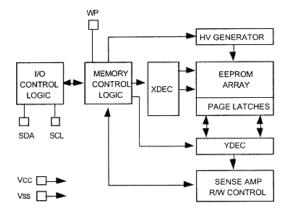


Figure 1. Representative Block Diagram





24AA02B Block Diagram

ELECTRICAL CHARACTERISTICS

24AA02A Block Diagram

Maximum Ratings

| Parameter | Value |
|--|--------------------------------|
| V _{CC} | 7.0 V |
| All inputs and outputs w.r.t.V _{ss} | -0.3V to V _{CC} +1.0V |
| Storage temperature | -65°C to +150°C |
| Ambient temp. with power applied | -40°C to +85°C |

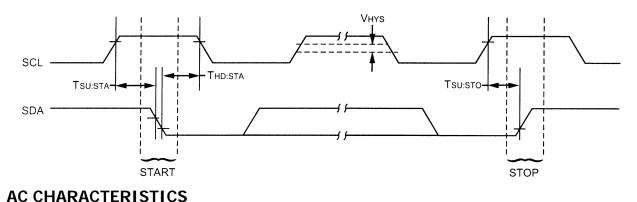
DC CHARACTERISTICS

| $V_{cc} = +1.8V$ to $+5.5V$, Tamb = $-40^{\circ}C$ to $+85^{\circ}C$ | | | | | | |
|---|----------------------|--------------|-------------|-------|-----------------------------------|--|
| | T | | | | | |
| Parameter | Symbol | Min | Max | Units | Mode | |
| WP, SCL and SDA pins: | | | | | | |
| High level input voltage | V _{IH} | $0.7V_{CC}$ | - | V | | |
| Low level input voltage | V _{IL} | - | $0.3V_{CC}$ | V | | |
| Hysteresis of Schmitt trigger inputs | V _{HYS} | $0.05V_{CC}$ | - | V | (Note) | |
| Low level output voltage | V _{OL} | - | 0.40 | V | I_{OL} = 3.0mA, V_{CC} = 2.5V | |
| Input leakage current | ILI | - | ±1 | μA | $V_{IN} = V_{SS}$ to V_{CC} | |
| Output leakage current | I _{LO} | - | ±1 | μA | $V_{OUT} = V_{ss}$ to V_{CC} | |
| Pin capacitance (all inputs/outputs) | CIN | | 10 | ъГ | V _{cc} =5.0V (Note) | |
| | C _{OUT} | - | 10 | рF | Tamb=25°C, F _{CLK} =1MHz | |
| Operating current | I_{CC} WRITE | - | 3 | mA | V_{CC} =5.5V, SCL=400kHz | |
| | I _{CC} READ | - | 1 | mA | - | |
| Standby current | I _{CCS} | - | 1 | μA | $SDA=SCL=V_{CC}, WP=V_{SS}$ | |

Note: This parameter is periodically sampled and not 100% tested.



Figure 2. Bus timing Start/Stop



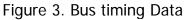
| | | 1.8≤V _{cc} | <2.5V | 2.5≤V _c | 2.5≤V _{cc} ≤5.5V | | |
|---|---------------------|---------------------|-------|----------------------|---------------------------|-------|---|
| Parameter | Symbol | Min | Max | Min | Max | Units | Remarks |
| Clock frequency | F _{CLK} | - | 100 | - | 400 | kHz | |
| Clock high time | T _{HIGH} | 4000 | - | 600 | - | ns | |
| Clock low time | T _{LOW} | 4700 | - | 1300 | - | ns | |
| SDA and SCL rise time | T _R | - | 1000 | - | 300 | ns | Note 2 |
| SDA and SCL fall time | T_F | - | 300 | - | 300 | ns | Note 2 |
| START condition hold time | T _{hd:sta} | 4000 | - | 600 | - | ns | After this period the first clock pulse is generated |
| START condition setup time | T _{su:sta} | 4700 | - | 600 | - | ns | Only relevant for repeated START condition |
| Data input hold time | T _{HD:DAT} | 0 | - | 0 | - | ns | Note 1 |
| Data input setup time | T _{SU:DAT} | 250 | - | 100 | - | ns | |
| STOP condition setup time | T _{SU:STO} | 4000 | - | 600 | - | ns | |
| Output valid from clock | T_{AA} | - | 3500 | - | 900 | ns | Note 1 |
| Bus free time | T _{BUF} | 4700 | - | 1300 | - | ns | Time the bus must be free before a new transmission can start |
| Output fall time from V _{IH} min to V _{IL} max | T _{OF} | - | 250 | 20+0.1C _B | 250 | ns | C _B ≤100pF (Note2) |
| Input filter spike suppres-sion (SDA & SCL pins) | T _{SP} | - | 50 | - | 50 | ns | Note 3 |
| Write cycle time | T_{WR} | - | 5 | - | 5 | ms | Byte or Page mode |

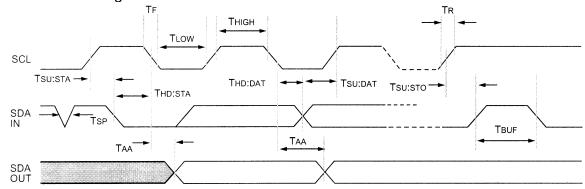
Note 1: As a transmitter, the device must provide an internal minimum delay time to bridge the undefined region (minimum 300 ns) of the falling edge of SCL to avoid unintended generation of START or STOP conditions.

Note 2: Not 100% tested. C_B = total capacitance of one bus line in pF.

Note 3: The combined TSP and VHYS specifications are due to new Schmitt trigger inputs that provide improved noise and spike suppression. This eliminates the need for a Ti specification for standard operation.







FUNCTIONAL DESCRIPTION

The IN24AA02 supports a bi-directional two-wire bus and data transmission protocol. A device that sends data onto the bus is defined as transmitter, and a device receiving data as receiver. The bus has to be controlled by a master device that generates the serial clock (SCL), controls the bus access, and generates the START and STOP conditions, while the IN24AA02 works as slave. Both, master and slave can operate as transmitter or receiver but the master device determines which mode is activated.

BUS CHARACTERISTICS

The following bus protocol has been defined:

- Data transfer may be initiated only when the bus is not busy.
- During data transfer, the data line must remain stable whenever the clock line is HIGH. Changes in the data line while the clock line is HIGH will be interpreted as a START or STOP condition.

Accordingly, the following bus conditions have been defined (see Figure 4).

Bus not Busy (A)

Both data and clock lines remain HIGH.

Start Data Transfer (B)

A HIGH to LOW transition of the SDA line while the clock (SCL) is HIGH determines a START condition. All commands must be preceded by a START condition.

Stop Data Transfer (C)

A LOW to HIGH transition of the SDA line while the clock (SCL) is HIGH determines a STOP condition. All operations must be ended with a STOP condition.

Data Valid (D)

The state of the data line represents valid data when, after a START condition, the data line is stable for the duration of the HIGH period of the clock signal.

The data on the line must be changed during the LOW period of the clock signal. There is one clock pulse per bit of data.

Each data transfer is initiated with a START condition and terminated with a STOP condition. The number of the data bytes transferred between the START and STOP conditions is determined by the master device and is theoretically unlimited, although



only the last sixteen will be stored when doing a write operation. When an overwrite does occur it will replace data in a first in first out fashion.

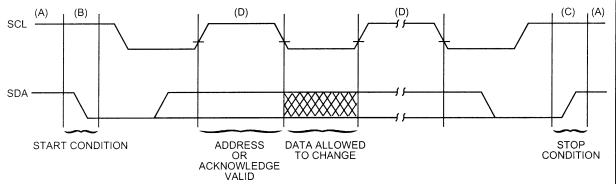
Acknowledge

Each receiving device, when addressed, is obliged to generate an acknowledge after the reception of each byte. The master device must generate an extra clock pulse which is associated with this acknowledge bit.

Note: The IN24AA02 does not generate any acknowledge bits if an internal programming cycle is in progress

The device that acknowledges, has to pull down the SDA line during the acknowledge clock pulse in such a way that the SDA line is stable LOW during the HIGH period of the acknowledge related clock pulse. Of course, setup and hold times must be taken into account. A master must signal an end of data to the slave by not generating an acknowledge bit on the last byte that has been clocked out of the slave. In this case, the slave must leave the data line HIGH to enable the master to generate the STOP condition.





BUS CHARACTERISTICS Slave Address

The IN24AA02 are software-compatible with devices such as 24C01A, 24C02A, 24LC01, and 24LC02. A single 24AA02 can be used in place of two 24AA01's, for example, without any modifications to software. The "chip select" portion of the control byte becomes don't care.

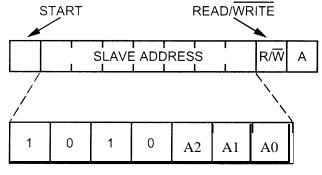
After generating a START condition, the bus master transmits the slave address consisting of a 4-bit device code (1010) for the IN24AA02, followed by three bits address selection (In a case of IN24AA02B these three bits can be anyone). The eighth bit of slave address determines if the master device wants to read or write to the IN24AA02 (see Figure 5).

The IN24AA02 monitors the bus for its corresponding slave address all the time. It generates an acknowledge bit if the slave address was true and it is not in a programming mode.



| Operation | Control Code | Chip Select | R/W |
|---------------|--------------|-------------|-----|
| For IN24AA02A | | | |
| Read | 1010 | A2 A1 A0 | 1 |
| Write | 1010 | A2 A1 A0 | 0 |
| For IN24AA02B | | | |
| Read | 1010 | X X X | 1 |
| Write | 1010 | X X X | 0 |

Figure 5. Control Byte Allocation



WRITE OPERATION

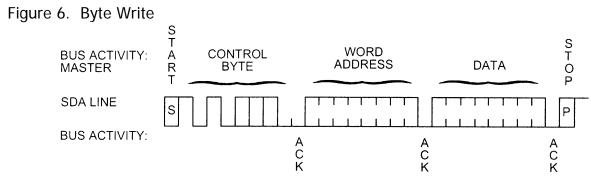
Byte Write

Following the start condition from the master, the device code (4 bits), the device address selection (3 bits), and the R/W bit, which is a logic low, is placed onto the bus by the master transmitter. This indicates to the addressed slave receiver that a byte with a word address will follow after it has generated an acknowledge bit during the ninth clock cycle. Therefore the next byte transmitted by the master is the word address and will be written into the address pointer of the IN24AA02. After receiving another acknowledge signal from the IN24AA02 the master device will transmit the data word to be written into the addressed memory location. The IN24AA02 acknowledges again and the master generates a stop condition. These initiates the internal write cycle, and during this time the IN24AA02 will not generate acknowledge signals (see Figure 6).

Page Write

The write control byte, word address and the first data byte are transmitted to the IN24AA02 in the same way as in a byte write. But instead of generating a stop condition the master transmits up to eight data bytes to the IN24AA02, which are temporarily stored in the on-chip page buffer and will be written into the memory after the master has transmitted a stop condition. After the receipt of each word, the three lower order address pointer bits are internally incremented by one. The higher order five bits of the word address remains constant. If the master should transmit more than eight words prior to generating the stop condition, the address counter will roll over and the previously received data will be overwritten. As with the byte write operation, once the stop condition is received an internal write cycle will begin (see Figure 8).





ACKNOWLEDGE POLLING

Since the device will not acknowledge during a write cycle, this can be used to determine when the cycle is complete (this feature can be used to maximize bus throughput). Once the stop conditions for a write Figure 7. Acknowledge Polling Flow

Once the stop conditions for a write command has been issued from the master, the device initiates the internally timed write cycle, ACK polling can be initiated immediately. This involves the master sending a start condition followed by the control byte for a write command (R/W =0). If the device is still busy with the write cycle, then no ACK will be returned. If the cycle is complete, then the device will return the ACK and the master can then proceed with the next read or write command. See Figure 7 for flow diagram.

WRITE PROTECTION

The IN24AA02 can be used as a serial ROM when the WP pin is connected to V_{CC} . Programming will be inhibited and the entire memory will be write-protected.

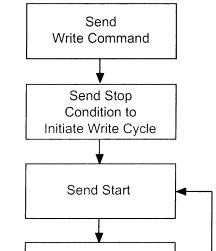
READ OPERATION

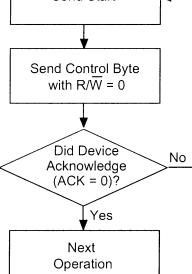
Read operations are initiated in the same way as write operations with the exception that the R/W bit of the slave address is set to one. There are three basic types of read operations: current address read, random read, and sequential read.

CURRENT ADDRESS READ

The IN24AA02 contains an address counter that maintains the address of the last word accessed, internally incremented by one. Therefore, if the previous access (either a read or write operation) was to address n, the next current address read operation would access data from address n+1. Upon receipt of the slave address with R/W bit set to one, the IN24AA02 issues an acknowledge and transmits the eight bit data word. The







master will not acknowledge the transfer but does generate a stop condition and the IN24AA02 discontinues transmission (see Figure 9).

RANDOM READ

Random read operations allow the master to access any memory location in a random manner. To perform this type of read operation, first the word address must be set. Sending the word address to the IN24AA02 as part of a write operation does this. After the word address is sent, the master generates a start condition following the acknowledge. This terminates the write operation, but not before the internal address pointer is set. Then the master issues the control byte again but with the R/W bit set to a one. The IN24AA02 will then issue an acknowledge and transmits the eight bit data word. The master will not acknowledge the transfer but does generate a stop condition and the IN24AA02 discontinues transmission (see Figure 10).

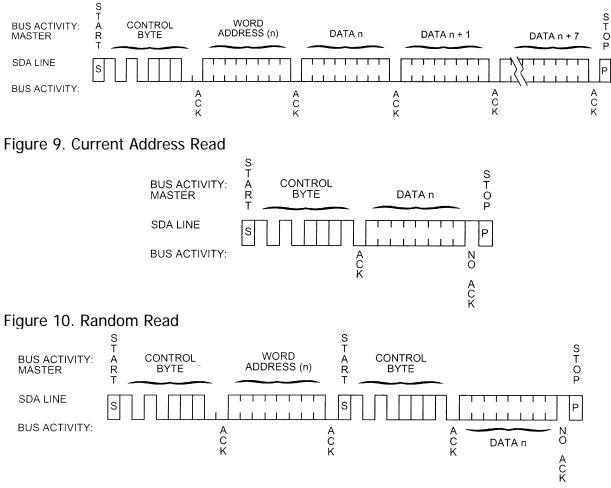


Figure 8. Page Write

SEQUENTIAL READ

Sequential reads are initiated in the same way as a random read except that after the IN24AA02 transmits the first data byte, the master issues an acknowledge as opposed to a stop condition in a random read. This directs the IN24AA02 to transmit the next sequentially addressed 8 bit word (see Figure 11).

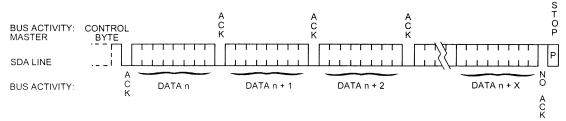


To provide sequential reads the IN24AA02 contains an internal address pointer, which is incremented by one at the completion of each operation. This address pointer allows the entire memory contents to be serially read during one operation.

NOISE PROTECTION

The SCL and SDA inputs have Schmitt trigger and filter circuits, which suppress noise spikes to assure proper device operation even on a noisy bus.

Figure 11. Sequential read



PIN DESCRIPTIONS

SDA Serial Address/Data Input/Output

This is a bi-directional pin used to transfer addresses and data into and data out of the device. It is an open drain terminal, therefore the SDA bus requires a pull-up resistor to V_{CC} (typical 4.7K Ω for 100kHz, 1K Ω for 400kHz).

For normal data transfer SDA is allowed to change only during SCL low. Changes during SCL high are reserved for indicating the START and STOP conditions.

SCL Serial Clock

This input is used to synchronize the data transfer from and to the device.

WP

This pin must be connected to either V_{SS} or V_{CC} .

If tied to V_{SS}, normal memory operation is enabled (read/write the entire memory).

If tied to V_{CC} , WRITE operations are inhibited. The entire memory will be write-protected. Read operations are not affected.

This feature allows the user to use the IN24AA02 as a serial ROM when WP is enabled (tied to V_{cc}). This pin is internally pulled down to V_{ss} .

AO, A1, A2

For IN24AA02A these inputs are used to device address selection. These pins are internally pulled down to $V_{\text{SS}}.$

For IN24AA02B these inputs are not used. They may be left floating or tied to either V_{SS} or $V_{\text{CC}}.$



TYPICAL CONFIGURATION

Using the A0, A1, and A2 input pins (IN24AA02A), up to eight devices can be connected to the same two-ware bus as slaves (see figure 12). On the contrary only one IN24AA02B can be connected to the two-ware bus as the slave (see figure 13).

Figure 12. Typical Configuration for IN24AA02A

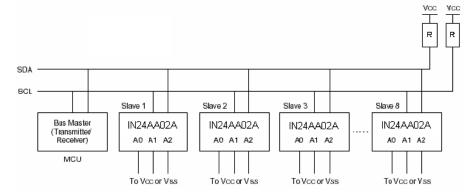
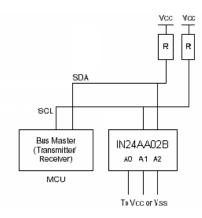


Figure 13. Typical Configuration for IN24AA02B



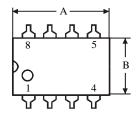
Ordering information

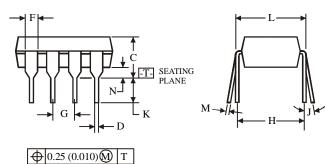
| Туре | Description | Ordering code | Package | Packing | Standard |
|--------------|-----------------------|---------------|-----------|-------------|------------|
| | | | | | of packing |
| | 2K Bits, 1.8-5.5V, | IN24AA02AN | DIP-8 | Tube | 49 |
| | | IN24AA02AD | SOIC-8 | Tube | 97 |
| IN24AA02A | -40°C to +85°C, | IN24AA02ADR1 | SOIC-8 | Tape & Reel | 2500 |
| Address pins | • | IN24AA02ADR2 | SOIC-8 | | 4000 |
| | are used | | Chip on w | afer (6") | |
| | 2K Bits, | IN24AA02BN | DIP-8 | Tube | 49 |
| | 1.8-5.5V, | IN24AA02BD | SOIC-8 | Tube | 97 |
| IN24AA02B | -40°C to +85°C, | IN24AA02BDR1 | SOIC-8 | | 2500 |
| | Address pins | IN24AA02BDR2 | SOIC-8 | Tape & Reel | 4000 |
| are not used | | IN24AA02B | Chip on w | afer (6") | |



IN24AA02

N SUFFIX PLASTIC DIP (MS – 001BA)



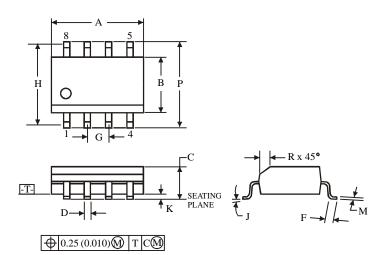


| | Symbol | Dimens | sin, mm |
|--------------------------------------|--------|--------|---------|
| | | min | max |
| NOT ES: 1. Di m en si | А | 8.51 | 10.16 |
| | В | 6.10 | 7.11 |
| | С | | 5.33 |
| | D | 0.36 | 0.56 |
| | F | 1.14 | 1.78 |
| on | G | 2. | 54 |
| S | Н | 7. | 62 |
| "A ", | J | 0° | 10° |
| "B | К | 2.92 | 3.81 |
| " do | L | 7.62 | 8.26 |
| no | М | 0.20 | 0.36 |
| t in | Ν | 0.38 | |

Maximum mold flash or protrusions

clude mold flash or protrusions. 0.25 mm (0.010) per side.

D SUFFIX SOIC (MS - 012AA)



NOTES:

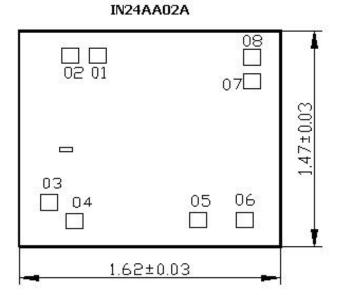
- 1. Dimensions A and B do not include mold flash or protrusion.
- 2. Maximum mold flash or protrusion 0.15 mm (0.006) per side for A; for B 0.25 mm (0.010) per side.

| Symb | Dimens | sin, mm | |
|------|--------|---------|--|
| | min | max | |
| Α | 4.80 | 5.00 | |
| В | 3.80 | 4.00 | |
| С | 1.35 | 1.75 | |
| D | 0.33 | 0.51 | |
| F | 0.40 | 1.27 | |
| G | 1.27 | | |
| н | 5. | 72 | |
| J | 0° | 8° | |
| к | 0.10 | 0.25 | |
| М | 0.19 | 0.25 | |
| Р | 5.80 | 6.20 | |
| R | 0.25 | 0.50 | |



11

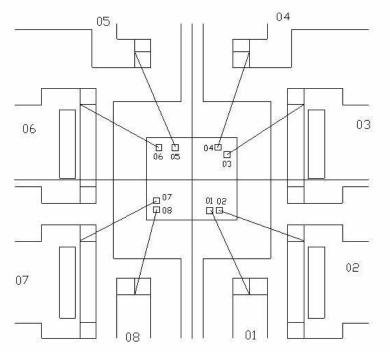
IN24AA02A Chip Diagram



Pad location

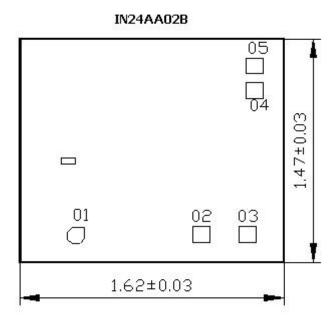
| | - | | | | |
|--------|--------|--------|--------|--------|--------|
| Pad No | X, mkm | Y, mkm | Pad No | X, mkm | Y, mkm |
| 1 | 423 | 1274 | 5 | 1068 | 105 |
| 2 | 245 | 1272 | 6 | 1366 | 105 |
| 3 | 106 | 232 | 7 | 1411 | 1092 |
| 4 | 272 | 101 | 8 | 1411 | 1260 |

IN24AA02A Bonding Diagram





IN24AA02B Chip Diagram



Pad location

| Pad No | X, mkm | Y, mkm | Pad No | X, mkm | Y, mkm |
|--------|--------|--------|--------|--------|--------|
| 01 | 272 | 101 | 04 | 1411 | 1.092 |
| 02 | 1068 | 105 | 05 | 1411 | 1260 |
| 03 | 1.366 | 0.105 | | | |

IN24AA02B Bonding Diagram

